

LMC7101Q-Q1 Automotive, Tiny, Low-Power Operational Amplifier With Rail-to-Rail Input and Output

1 Features

- AEC-Q100 qualified for automotive applications: Temperature: –40°C to +125°C, T_A
- Tiny 5-Pin SOT-23 package saves space; typical circuit layouts take half the space of 8-pin SOIC designs
- Specified for 2.7V, 3V, 5V, 15V supplies
- Typical supply current 0.5mA at 5V
- Typical total harmonic distortion of 0.01% at 5V
- 1MHz gain bandwidth
- Similar to popular LMC6482 and LMC6484
- Rail-to-rail input and output

2 Applications

- Mobile communications
- Notebooks and PDAs
- Battery-powered products
- Sensor interface
- Automotive applications

3 Description

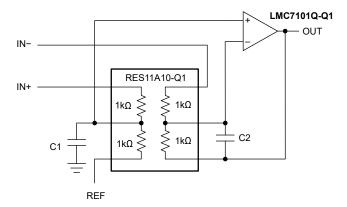
The LMC7101Q-Q1 device is a high-performance, automotive, CMOS operational amplifier available in a space-saving, 5-pin, SOT-23 tiny package. This design makes the LMC7101Q-Q1 an excellent choice for space- and weight-critical designs. The performance is similar to the single amplifier of the LMC6482 and LMC6484, with rail-to-rail input and output, high open-loop gain, low distortion, and lowsupply currents.

The main benefits of the tiny package are most apparent in space-constrained applications. The tiny amplifiers can be placed on a board where needed, thus simplifying board layout.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE(2)
LMC7101Q-Q1	DBV (SOT-23, 5)	2.9mm × 2.8mm

- For more information, see Section 10. (1)
- The package size (length × width) is a nominal value and includes pins, where applicable.



Difference Amplifier Application With RES11A-Q1



Table of Contents

1 Features1	6.2 Functional Block Diagram	20
2 Applications1	6.3 Feature Description	
3 Description1	6.4 Device Functional Modes	
4 Pin Configuration and Functions2	7 Application and Implementation	22
5 Specifications3	7.1 Application Information	
5.1 Absolute Maximum Ratings3	7.2 Typical Application	
5.2 ESD Ratings3	7.3 Power Supply Recommendations	
5.3 Recommended Operating Conditions3	7.4 Layout	25
5.4 Thermal Information3	8 Device and Documentation Support	
5.5 Electrical Characteristics for V _S = 2.7V or ±1.35V4	8.1 Documentation Support	26
5.6 Electrical Characteristics for V _S = 3V or ±1.5V5	8.2 Receiving Notification of Documentation Updates.	26
5.7 Electrical Characteristics for V _S = 5V or ±2.5V6	8.3 Support Resources	26
5.8 Electrical Characteristics for V _S = 15V or ±7.5V7	8.4 Trademarks	
5.9 Typical Characteristics for V _S = 2.7V9	8.5 Electrostatic Discharge Caution	26
5.10 Typical Characteristics for V _S = 3V11	8.6 Glossary	26
5.11 Typical Characteristics for V _S = 5V	9 Revision History	26
5.12 Typical Characteristics for V _S = 15V13	10 Mechanical, Packaging, and Orderable	
6 Detailed Description20	Information	27
6.1 Overview		

4 Pin Configuration and Functions

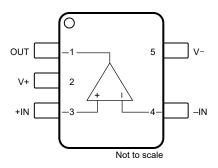


Figure 4-1. DBV Package, 5-Pin SOT-23 (Top View)

Table 4-1. Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME	1175	DESCRIP HON
1	OUT	Output	Output
2	V+	Power	Positive supply
3	+IN	Input	Noninverting input
4	-IN	Input	Inverting input
5	V-	Power	Negative supply

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1) (2)

	3 1 3 (MIN	MAX	UNIT
	Difference Input voltage		±Supply voltage	V
	Voltage at input and output pins	(V-) - 0.3	(V+) + 0.3	V
Vs	Supply voltage, $V_S = (V+) - (V-)$		16	V
	Current at input pin	-5	5	mA
	Current at output pin ⁽³⁾	-35	35	mA
	Current at power supply pin		35	mA
	Lead temperature (soldering, 10s)		260	°C
TJ	Junction temperature ⁽⁴⁾		150	°C
T _{stg}	Storage temperature	-65	150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) If Military/Aerospace specified devices are required, contact the TI Sales Office or Distributors for availability and specifications.
- (3) Applies to both single-supply and split-supply operation. Continuous short operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature at 150°C
- (4) The maximum power dissipation is a function of T_{J(MAX)}, R_{θ,JA} and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_J(_{MAX)} T_A) / R_{θ,JA}. All numbers apply for packages soldered directly into a PC board.

5.2 ESD Ratings

			VALUE	UNIT
V	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±1000	V
V _(ESD)	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101	±1000	V

⁽¹⁾ AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM MAX	UNIT
Vs	Supply voltage, V _S = (V+) – (V–)	2.7	15.5	V
T _A	Ambient temperature	-40	125	°C

5.4 Thermal Information

		LMC7101Q-Q1	
	THERMAL METRIC ⁽¹⁾		UNIT
		5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	193.5	°C/W
R _{θJC(top)}	Junction-to-case(top) thermal resistance	128.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	88.9	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	66.8	°C/W
ΨЈВ	Junction-to-board characterization parameter	88.6	°C/W
R _{θJC(bot)}	Junction-to-case(bottom) thermal resistance	N/A	°C/W

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

Copyright © 2025 Texas Instruments Incorporated



5.5 Electrical Characteristics for V_S = 2.7V or $\pm 1.35V$ at T_A = 25°C, V+ = 2.7V, V- = 0V, V_{CM} = V_{OUT} = V+ / 2, and R_L = 1M Ω connected to V+ / 2 (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
OFFSET	VOLTAGE						
Vos	Input offset voltage				±0.11	±9	mV
dV _{OS} /dT	Input offset voltage drift	T _A = -40°C to +125°C			1		μV/°C
PSRR	Power-supply rejection ratio	V+ = 1.35V to 1.65V, V- = -1.35V to -1.65V, V _{CM} = 0V		45	60		dB
INPUT BI	AS CURRENT					'	
I _B	Input bias current				±1		pА
в	input bias current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$				±1000	- PΛ
Ios	Input offset current				±0.5		pА
108	input onset current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$				±2000	p/ \
INPUT VO	DLTAGE						
V_{CM}	Common-mode voltage	For CMRR ≥ 47dB	Positive	2.7	3		V
* CIVI	Common mode voltage	TOTOWNING TOD	Negative		0	0	
CMRR	Common-mode rejection	$0V \le V_{CM} \le 2.7V$		47	70		dB
INPUT IM	PEDANCE						
R _{IN}	Input resistance				> 1		ΤΩ
C _{IN}	Common-mode input capacitance				3		pF
FREQUE	NCY RESPONSE						
GBW	Gain bandwidth product				0.6		MHz
SR	Slew rate ⁽¹⁾	V+ = 15V, 10V step, G = 1, F V _{OUT} = 10V _{PP} , f = 1kHz	$R_{L} = 100 k\Omega$ to 7.5V,		0.7		V/µs
OUTPUT							
		Positive rail	$R_L = 2k\Omega$	2.15	2.45		
Vo	Voltage output swing	1 OSIGVE TAII	$R_L = 10k\Omega$	2.64	2.68		V
VO.	voitage output swing	Negative rail	$R_L = 2k\Omega$		0.25	0.5	v
		rvegative rail	$R_L = 10k\Omega$		0.025	0.06	
POWER S	SUPPLY						
1-	Quiescent current per				500	810	μA
IQ	amplifier	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$			500	950	μΑ

⁽¹⁾ Number specified is the slower of the positive and negative slew rates.



5.6 Electrical Characteristics for V_S = 3V or ±1.5V at T_A = 25°C, V+ = 3V, V- = 0V, V_{CM} = 1.5V, V_{OUT} = V+ / 2, and R_L = 1M Ω connected to V+ / 2 (unless otherwise noted)

	PARAMETER	TES	ST CONDITIONS	MIN	TYP	MAX	UNIT	
OFFSET	VOLTAGE	-		•				
Vos	Input offset voltage				±0.11	±7	mV	
dV _{OS} /dT	Input offset voltage drift	T _A = -40°C to +125°C			1		μV/°C	
PSRR	Power-supply rejection ratio	V+ = 1.5V to 7.5V, V- = -1.5V to -7.5V, V _{OUT} = V _{CM} = 0V		60	80		dB	
INPUT BI	IAS CURRENT							
	I				±1		^	
I _B	Input bias current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$				±1000	рA	
	Innut effect oursent				±0.5			
los	Input offset current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	°C to +125°C			±2000	рA	
INPUT V	OLTAGE							
V	Input common-mode	For CMRR ≥ 47dB	Positive	3	3.3		V	
V _{CM}	voltage	FOR CMRR ≥ 47dB	Negative		0	0		
CMRR	Common-mode rejection	$0V \le V_{CM} \le 3V$		47	70		dB	
INPUT IM	IPEDANCE							
R _{IN}	Input resistance				> 1		ΤΩ	
C _{IN}	Common-mode input capacitance				3		pF	
OUTPUT						'		
		Positive rail	$R_L = 2k\Omega$	2.6	2.8			
V	Voltage output outpu		$R_L = 600\Omega$	2.5	2.7		V	
Vo	Voltage output swing	Nogotivo roil	$R_L = 2k\Omega$		0.2	0.4	V	
		Negative rail	R _L = 600Ω		0.37	0.6		
POWER S	SUPPLY		·					
1-	Quiescent current per				500	810		
IQ	amplifier	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$			500	950	μA 0	



5.7 Electrical Characteristics for V_S = 5V or $\pm 2.5V$ at T_A = 25°C, V+ = 5V, V- = 0V, V_{CM} = 1.5V, V_{OUT} = V+ / 2, and R_L = 1M Ω connected to V+ / 2 (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
OFFSET	VOLTAGE						
					±0.11	±7	
Vos	Input offset voltage	T _A = -40°C to +125°C			±0.11	±9	mV
dV _{OS} /dT	Input offset voltage drift	T _A = -40°C to +125°C			1		μV/°C
	mpar shoot remage ann	Positive		65	82		•
		V+ = 5V to 15V	T _A = -40°C to +125°C	62			
PSRR	Power supply rejection ratio	V- = 0V, V _{OUT} = 1.5V	1 _A = -40 C to +125 C		82		dB
		Negative V+ = -5V to -15V		65	82		
		$V = 0V, V_{OUT} = -1.5V$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	62	82		
INPUT BI	AS CURRENT		·				
	land bing somet				±1		^
I _B	Input bias current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$				±1000	pА
					±0.5		_
los	Input offset current	T _A = -40°C to +125°C				±2000	pА
NOISE							
THD	Total harmonic distortion	f = 10kHz, G = -2V/V, R _L = 1	$0k\Omega$, $V_{OLIT} = 4V_{pp}$		0.01		%
INPUT V	OLTAGE		у ост рр				
	Input common-mode voltage	To positive rail		5.2	5.3		
		CMRR > 50dB	T _A = -40°C to +125°C	4.8	5.3		
V_{CM}		To pogotivo roil		-	-0.3	-0.2	V
		To negative rail CMRR > 50dB	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		-0.3	0.2	
		0V ≤ V _{CM} ≤ 5V	1A 10 0 to 1120 0	52	75	0.2	
CMRR	Common-mode rejection ratio	$0.2V \le V_{CM} \le 4.8V, T_A = -40^{\circ}$	°C to +125°C	51	74		dB
INDIIT IN	 PEDANCE	0.2 v = v _{CM} = 4.0 v, 1 _A = -40	C 10 + 123 C	31			
					> 1		ΤΩ
R _{IN}	Input resistance						
CIN	Input capacitance				3		pF
	NCY RESPONSE						
GBW	Gain bandwidth product				1		MHz
SR	Slew rate				1		V/µs
OUTPUT							
		Positive rail		4.7	4.9		
		$R_L = 2k\Omega$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	4.54	4.9		
		Negative rail			0.1	0.18	
Vo	Voltage output swing	$R_L = 2k\Omega$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		0.1	0.28	V
•0	Tomago output oning	Positive rail		4.5	4.7		·
		$R_L = 600\Omega$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	4.28	4.7		
		Negative rail			0.3	0.5	
		$R_L = 600\Omega$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		0.3	0.8	
		Sourcing		16	24		
	Ob and almostic	$V_{OUT} = 0V$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	9	24		
I _{SC}	Short-circuit current	Sinking		11	19		mA
		V _{OUT} = 5V	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	5.8	19		
POWER	SUPPLY	1			,		
	Quiescent current per				0.5	0.85	
							mA



5.8 Electrical Characteristics for V_S = 15V or ±7.5V

at T_A = 25°C, V+ = 15V, V- = 0V, V_{CM} = 1.5V, V_{OUT} = V+ / 2, and R_L = 1M Ω connected to V+ / 2 (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS	MIN	TYP	MAX	UNIT	
OFFSET	VOLTAGE							
V _{OS}	Input offset voltage				±0.26		mV	
dV _{OS} /dT	Input offset voltage drift	T _A = -40°C to +125°C			1		μV/°C	
		Positive		62	82			
PSRR	Power-supply rejection	V+ = 5V to 15V, V- = 0V, V _{OUT} = 1.5V	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	60	82		dB	
FORK	ratio	Negative		65	82		uБ	
		V+ = -5V to -15V, $V- = 0V, V_{OUT} = -1.5V$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	62	82			
INPUT BI	AS CURRENT							
1_	Input bias current				±1		pА	
I _B	input bias current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$				±1000	рΑ	
l	Input offset current				±0.5		pА	
los	input onset current	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	-40°C to +125°C			±2000	РΑ	
NOISE		,						
e _n	Input voltage noise density	f = 1kHz, V _{CM} = 1V			37		nV/√ Hz	
i _n	Input current noise density	f = 1kHz			6.8		fA/√Hz	
THD	Total harmonic distortion	$f = 1kHz$, $G = -2V/V$, $R_L = 10k\Omega$,	$V_{OUT} = 8.5V_{pp}$		0.01		%	
INPUT V	OLTAGE							
	Input common-mode	To positive rail		15.2	15.3			
V _{CM}		Input common-mode	V+ = 15V, CMRR > 50dB	$T_A = -40^{\circ}C \text{ to } +125^{\circ}C$	14.8	15.3		V
V CM	voltage	To negative rail			-0.3	-0.2	V	
		V+ = 15V, CMRR > 50dB	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		-0.3	0.2		
CMRR	Common-mode rejection	0V ≤ V _{CM} ≤15V		62	82		dB	
CIVIKK	ratio	$0.2V \le V_{CM} \le 14.8V, T_A = -40^{\circ}C$	to +125°C	60	82		uБ	
INPUT IM	IPEDANCE							
R _{IN}	Input resistance				> 1		ΤΩ	
C _{IN}	Input capacitance				3		pF	
OPEN-LC	OOP GAIN							
		Sourcing		80	340			
		$7.5V < V_O < 12.5V, V_{CM} = 1.5V$ R _L = $2k\Omega$ to $7.5V$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	30	340			
۸	Open-loop voltage gain	Sinking		15	24		V/mV	
A _{OL}	Open-loop voltage galfi	$2.5V < V_O < 7.5V, V_{CM} = 1.5V$ R _L = $2k\Omega$ to $7.5V$	T _A = -40°C to +125°C	4	24		V/mV	
		Sourcing, V _{CM} = 1.5V, 7.5V < V _O	$< 12.5V, R_L = 600\Omega$	34	300			
		Sinking, V _{CM} = 1.5V, 2.5V < V _O <	7.5V, R _L = 600Ω	6	15			

Copyright © 2025 Texas Instruments Incorporated

Submit Document Feedback

5.8 Electrical Characteristics for $V_S = 15V$ or $\pm 7.5V$ (continued)

at T_A = 25°C, V+ = 15V, V- = 0V, V_{CM} = 1.5V, V_{OUT} = V+ / 2, and R_L = 1M Ω connected to V+ / 2 (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT	
FREQU	ENCY RESPONSE							
GBW	Gain bandwidth product				1.1		MHz	
	(0)	10V step,		0.5	1.1			
SR	Slew rate ⁽¹⁾	R_L = 100kΩ to 7.5V V _{OUT} = 10V _{PP} , f = 1kHz	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	0.4	1.1		V/µs	
θ_{m}	Phase margin				45		۰	
G _m	Gain margin				10		dB	
OUTPU	т							
	Voltage output swing	Positive rail		14.4	14.7			
		$R_L = 2k\Omega$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	14.2	14.7			
		Negative rail $R_L = 2k\Omega$			0.16	0.32		
Vo			$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		0.16	0.45	V	
v _O		Positive rail	Positive rail		13.4	14.1		V
		$R_L = 600\Omega$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	12.85	14.1			
		Negative rail			0.5	1		
		$R_L = 600\Omega$	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		0.5	1.5		
		Sourcing		30	50			
1	Short-circuit current ⁽²⁾	V _{OUT} = 0V	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	20	50		mA	
I _{SC}	Short-circuit current	Sinking		30	50		ША	
		V _{OUT} = 12V	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	20	50			
POWER	R SUPPLY							
	Quiescent current per				0.8	1.5	mA	
IQ	amplifier	T _A = -40°C to +125°C			0.8	1.75	IIIA	

⁽¹⁾ Number specified is the slower of the positive and negative slew rates.

⁽²⁾ Do not short circuit output to V+ when V+ is greater than 12V or reliability can be adversely affected.

5.9 Typical Characteristics for $V_S = 2.7V$

at V+ = 2.7V, V- = 0V, and T_A = 25°C (unless otherwise specified)

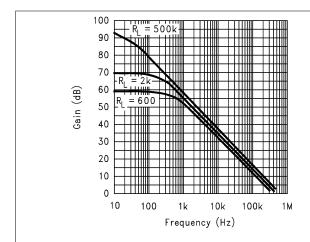


Figure 5-1. Open-Loop Frequency Response

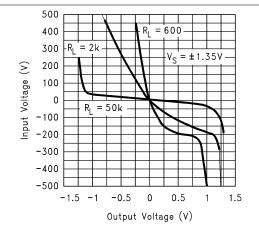


Figure 5-2. Input Voltage vs Output Voltage

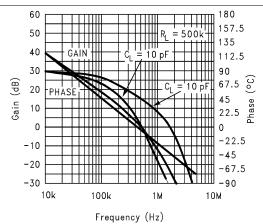


Figure 5-3. Gain and Phase vs Capacitance Load

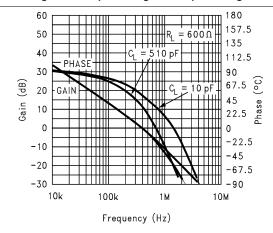


Figure 5-4. Gain and Phase vs Capacitance Load

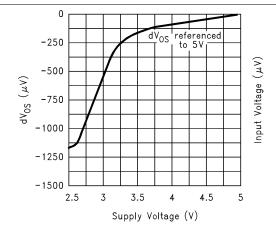


Figure 5-5. dV_{OS} vs Supply Voltage

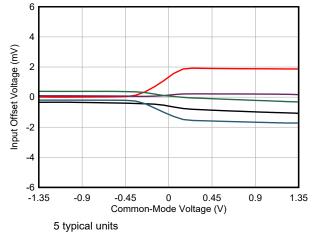
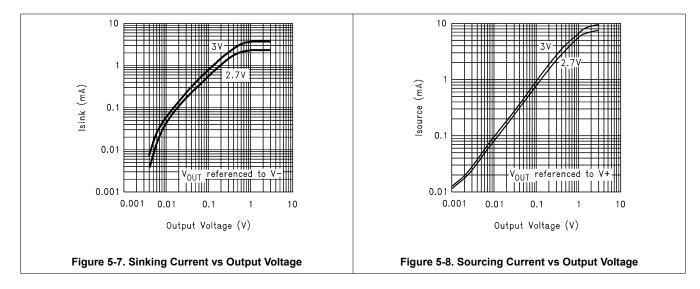


Figure 5-6. Input Offset Voltage vs Common-Mode Voltage



at V+ = 2.7V, V $_-$ = 0V, and T_A = 25°C (unless otherwise specified)





5.10 Typical Characteristics for $V_S = 3V$

at V+ = 3V, V- = 0V, and T_A = 25°C (unless otherwise specified)

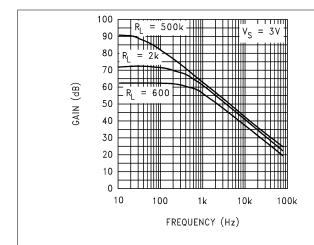


Figure 5-9. Open-Loop Frequency Response

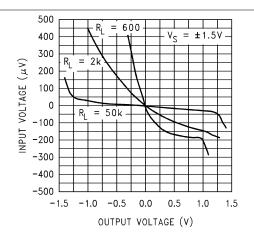


Figure 5-10. Input Voltage vs Output Voltage

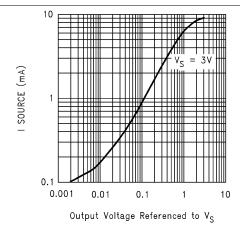


Figure 5-11. Sourcing Current vs Output Voltage

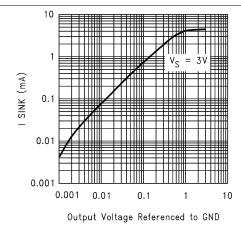


Figure 5-12. Sinking Current vs Output Voltage



5.11 Typical Characteristics for $V_S = 5V$

at V+ = 5V, V- = 0V, and T_A = 25°C (unless otherwise specified)

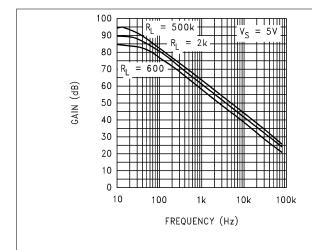


Figure 5-13. Open-Loop Frequency Response

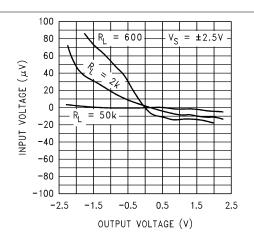


Figure 5-14. Input Voltage vs Output Voltage

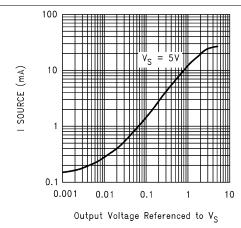


Figure 5-15. Sourcing Current vs Output Voltage

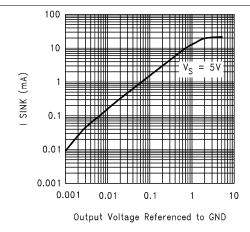


Figure 5-16. Sinking Current vs Output Voltage

Submit Document Feedback

Copyright © 2025 Texas Instruments Incorporated

5.12 Typical Characteristics for $V_S = 15V$

at V+ = 15V, V- = 0V, and T_A = 25°C (unless otherwise specified)

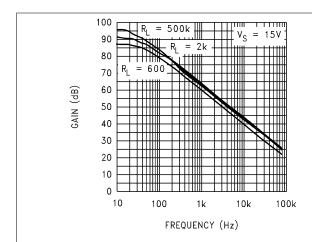


Figure 5-17. Open-Loop Frequency Response

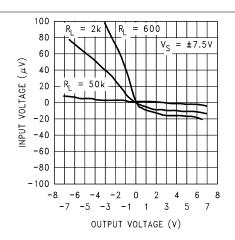


Figure 5-18. Input Voltage vs Output Voltage

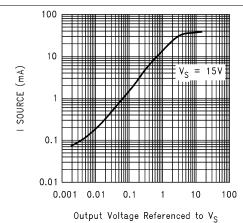


Figure 5-19. Sourcing Current vs Output Voltage

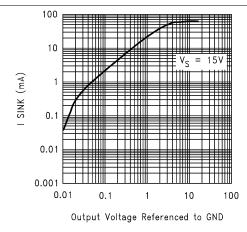
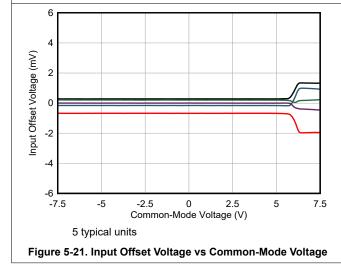


Figure 5-20. Sinking Current vs Output Voltage



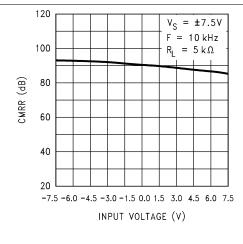
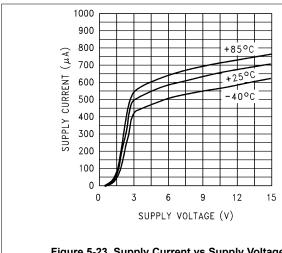


Figure 5-22. CMRR vs Input Voltage



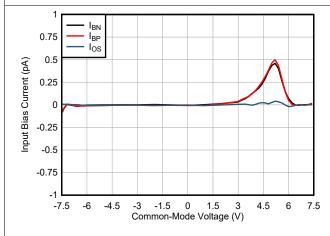
at V+ = 15V, V- = 0V, and T_A = 25°C (unless otherwise specified)



10000 1000 INPUT CURRENT (pA) 100 10 25 50 75 100 125 150 TEMPERATURE (°C)

Figure 5-23. Supply Current vs Supply Voltage

Figure 5-24. Input Current vs Temperature



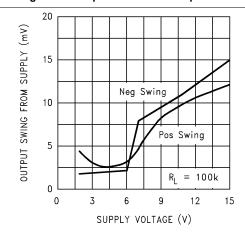
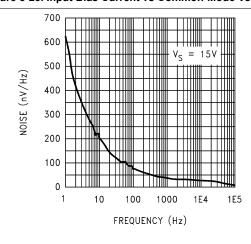


Figure 5-25. Input Bias Current vs Common-Mode Voltage

Figure 5-26. Output Voltage Swing vs Supply Voltage



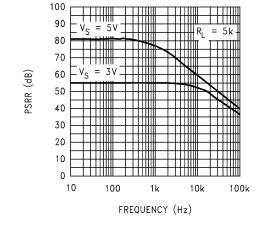


Figure 5-27. Input Voltage Noise vs Frequency

Figure 5-28. Positive PSRR vs Frequency



at V+ = 15V, V- = 0V, and T_A = 25°C (unless otherwise specified)

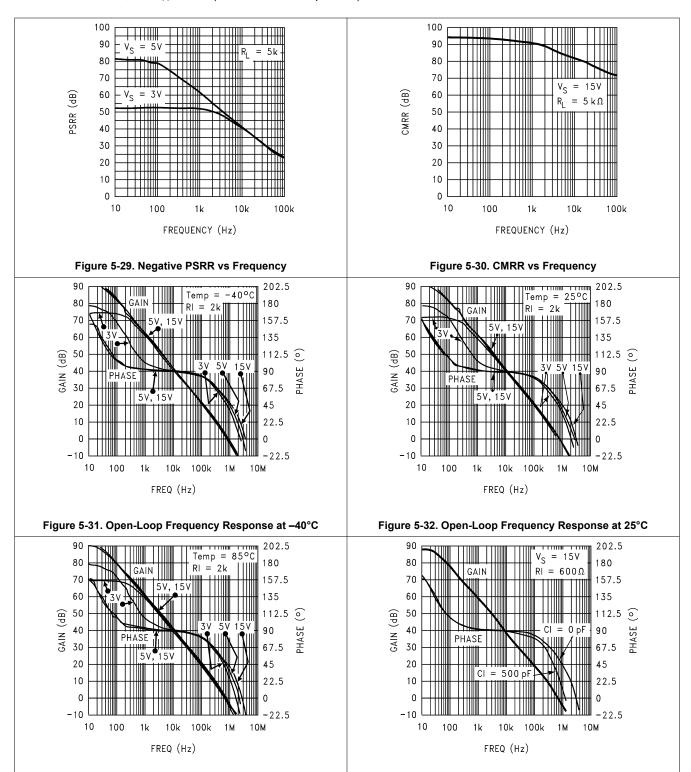
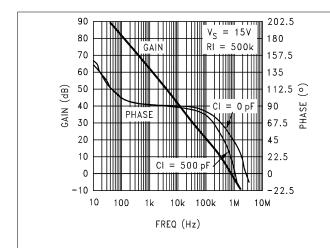


Figure 5-33. Open-Loop Frequency Response at 85°C

Figure 5-34. Gain and Phase vs Capacitive Load



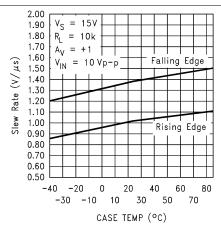
at V+ = 15V, V- = 0V, and T_A = 25°C (unless otherwise specified)



1000 900 800 OUTPUT IMPEDANCE (\Omega) 700 600 = 3V **∏** 500 400 300 157 200 100 0 1k 10k 100k 1 M FREQUENCY (Hz)

Figure 5-35. Gain and Phase vs Capacitive Load

Figure 5-36. Output Impedance vs Frequency



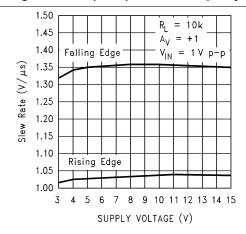
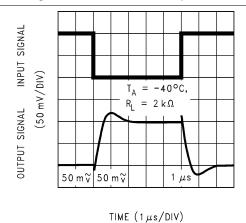


Figure 5-37. Slew Rate vs Temperature

Figure 5-38. Slew Rate vs Supply Voltage



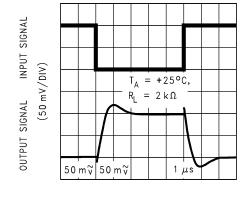


Figure 5-39. Inverting Small-Signal Pulse Response

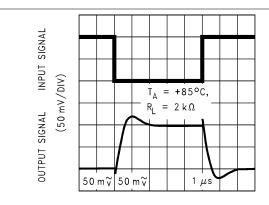
Figure 5-40. Inverting Small-Signal Pulse Response

TIME $(1\mu s/DIV)$

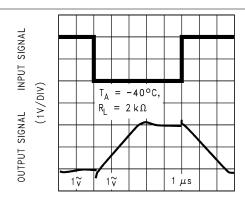
Submit Document Feedback

Copyright © 2025 Texas Instruments Incorporated

at V+ = 15V, V- = 0V, and T_A = 25°C (unless otherwise specified)



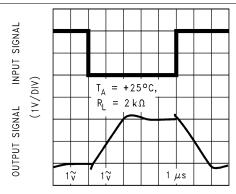
TIME $(1 \mu s/DIV)$



TIME $(1\mu s/DIV)$

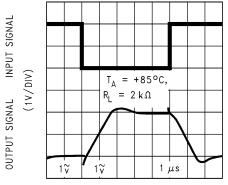
Figure 5-41. Inverting Small-Signal Pulse Response





TIME $(1\mu s/DIV)$

Figure 5-42. Inverting Large-Signal Pulse Response



TIME $(1\mu s/DIV)$

Figure 5-43. Inverting Large-Signal Pulse Response

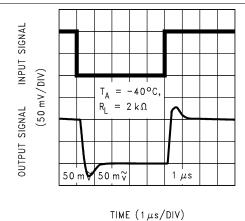
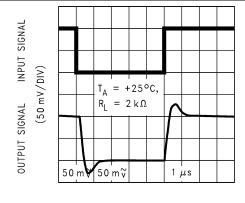


Figure 5-45. Noninverting Small-Signal Pulse Response



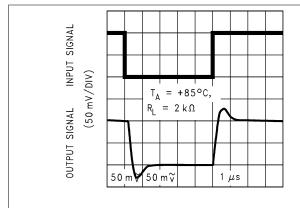


TIME $(1\mu s/DIV)$

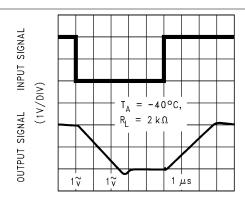
Figure 5-46. Noninverting Small-Signal Pulse Response



at V+ = 15V, V- = 0V, and T_A = 25°C (unless otherwise specified)

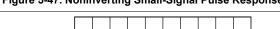


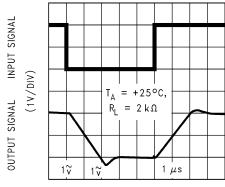
TIME $(1 \mu s/DIV)$



TIME $(1\mu s/DIV)$

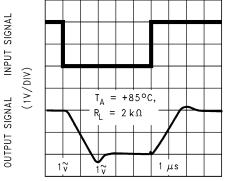
Figure 5-47. Noninverting Small-Signal Pulse Response





TIME $(1\mu s/DIV)$

Figure 5-48. Noninverting Large-Signal Pulse Response



TIME $(1\mu s/DIV)$

Figure 5-49. Noninverting Large-Signal Pulse Response

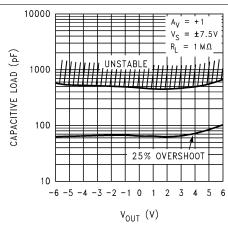


Figure 5-51. Stability vs Capacitive Load

Figure 5-50. Noninverting Large-Signal Pulse Response

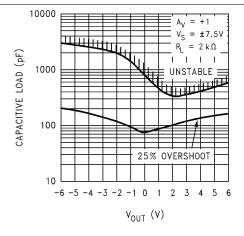


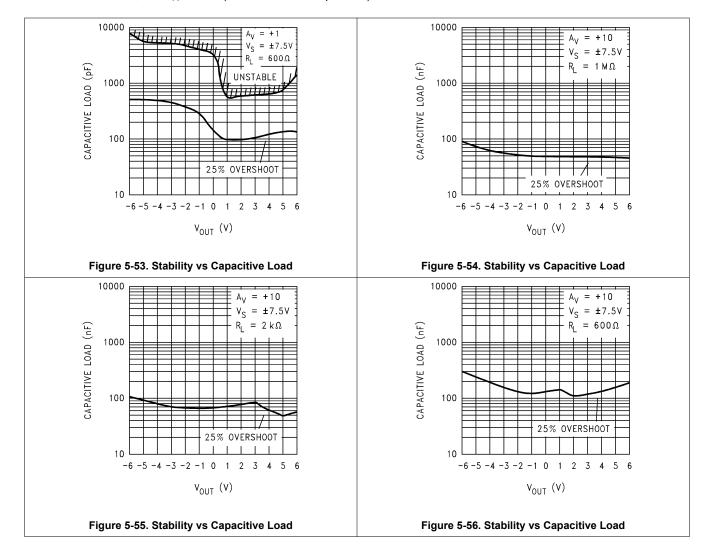
Figure 5-52. Stability vs Capacitive Load

Submit Document Feedback

Copyright © 2025 Texas Instruments Incorporated



at V+ = 15V, V- = 0V, and T_A = 25°C (unless otherwise specified)



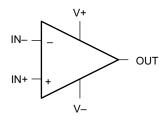
6 Detailed Description

6.1 Overview

The LMC7101Q-Q1 is a single-channel, low-power operational amplifier available in a space-saving SOT-23 package, offering rail-to-rail input and output operation across a wide range of power-supply configurations.

The LMC7101Q-Q1 is also available in a commercial-grade variant, see LMC7101.

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Benefits of the LMC7101 Tiny Amplifier

6.3.1.1 Size

The small footprint of the SOT-23-5 packaged tiny amplifier, (0.12in × 0.118in, 3.05mm × 3mm) saves space on printed circuit boards, and enable the design of smaller electronic products. Many customers prefer smaller and lighter products because the designs can contribute to overall weight reduction in vehicles.

6.3.1.2 Height

The 0.056 inches (1.43mm) height of the tiny LMC7101Q-Q1 amplifier makes the device an excellent choice for use in a wide range of circuit boards in which a thin profile is required.

6.3.1.3 Signal Integrity

Signals can pick up noise between the signal source and the amplifier. By using a physically smaller amplifier package, the tiny amplifier can be placed closer to the signal source, thus reducing noise pickup and increasing signal integrity. The tiny amplifier can also be placed next to the signal destination, such as a buffer, for the reference of an analog-to-digital converter.

6.3.1.4 Simplified Board Layout

The tiny LMC7101Q-Q1 amplifier can simplify board layout in several ways. Avoid long PCB traces by correctly placing amplifiers instead of routing signals to a dual or quad device. By using multiple tiny amplifiers instead of duals or quads, complex signal routing and possibly crosstalk can be reduced.

6.3.1.5 Low THD

The high open-loop gain of the LMC7101Q-Q1 amplifier helps to achieve very low audio distortion—typically 0.01% at 10kHz with a $10k\Omega$ load at 5V supplies. This makes the tiny amplifier an excellent choice for automotive audio and low-frequency signal-processing applications.

6.3.1.6 Low Supply Current

The typical 0.5mA supply current of the LMC7101Q-Q1 can help improve thermal performance on high density circuit boards, and can allow the reduction of the overall board size in some applications.

6.3.1.7 Wide Voltage Range

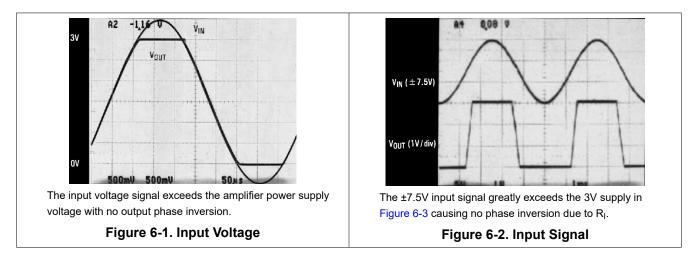
The LMC7101 is characterized at 15V, 5V and 3V. Performance data is provided at these popular voltages. This wide voltage range makes the LMC7101Q-Q1 a good choice for devices where the supply voltage can vary.

6.4 Device Functional Modes

6.4.1 Input Common-Mode Voltage Range

The LMC7101Q-Q1 does not exhibit phase inversion when an input voltage exceeds the negative supply voltage. Figure 6-1 shows an input voltage exceeding both supplies with no resulting phase inversion of the output.

The absolute maximum input voltage is 300mV beyond either rail at room temperature. Voltages greatly exceeding this maximum rating, as in Figure 6-2, can cause excessive current to flow in or out of the input pins, thus adversely affecting reliability.



Applications that exceed this rating must externally limit the maximum input current to ±5mA with an input resistor as shown in Figure 6-3.

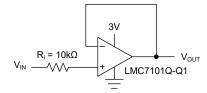


Figure 6-3. R_I Input Current Protection for Voltages Exceeding the Supply Voltage

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Application Information

7.1.1 Rail-to-Rail Output

The approximate output resistance of the LMC7101Q-Q1 is 180Ω sourcing and 130Ω sinking at $V_S = 3V$ and 110Ω sourcing and 80Ω sinking at $V_S = 5V$. Using the calculated output resistance, maximum output voltage swing can be estimated as a function of load.

7.1.2 Capacitive Load Tolerance

The LMC7101Q-Q1 can typically directly drive a 100pF load with $V_S = 15V$ at unity gain without oscillating. The unity gain follower is the most sensitive configuration. Direct capacitive loading reduces the phase margin of operational amplifiers. The combination of the output impedance and the capacitive load of the operational amplifier induces phase lag, which results in either an underdamped pulse response or oscillation.

Capacitive load compensation can be accomplished using resistive isolation as shown in Figure 7-1. This simple technique is useful for isolating the capacitive input of multiplexers and A/D converters.

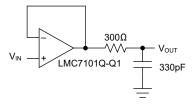


Figure 7-1. Resistive Isolation of a 330pF Capacitive Load

7.1.3 Compensating for Input Capacitance When Using Large Value Feedback Resistors

When using very large value feedback resistors, (usually >500 k Ω) the large feed back resistance can react with the input capacitance due to transducers, photo diodes, and circuit board parasitics to reduce phase margins.

The effect of input capacitance can be compensated for by adding a feedback capacitor. The feedback capacitor (as in Figure 7-2), C_f is first estimated by Equation 1 and Equation 2, which typically provides significant overcompensation.

$$\frac{1}{2\pi R_1 C_{IN}} \ge \frac{1}{2\pi R_2 C_f}$$
 (1)

$$2\pi R_1 C_{IN} \le 2\pi R_2 C_f \tag{2}$$

Printed circuit board stray capacitance can be larger or smaller than that of a breadboard, so the actual optimum value for C_F can be different. The values of C_F must be checked on the actual circuit.

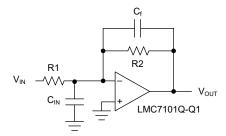


Figure 7-2. Canceling the Effect of Input Capacitance

7.2 Typical Application

Figure 7-3 shows a high input impedance noninverting circuit. This circuit gives a closed-loop gain equal to the ratio of the sum of R1 and R2 to R1 and a closed-loop 3dB bandwidth equal to the amplifier unity-gain frequency divided by the closed-loop gain. This design has the benefit of a very high input impedance, which is equal to the differential input impedance multiplied by loop gain (open loop gain / closed loop gain). In dc-coupled applications, input impedance is not as important as input current and the voltage drop across the source resistance. The amplifier output can go into saturation if the input is allowed to float, which can be important if the amplifier must be switched from source to source.

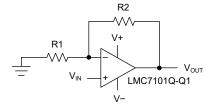


Figure 7-3. Example Application

7.2.1 Design Requirements

For this example application, the supply voltage is 5V, and 100 \times ±5% of noninverting gain is necessary. The signal input impedance is approximately 10k Ω .

7.2.2 Detailed Design Procedure

Use the equation for a noninverting amplifier configuration; G = 1 + R2 / R1, set R1 to $10k\Omega$, and R2 to $99 \times R1$, which is $990k\Omega$. Replacing the $990k\Omega$ resistor with a more readily available $1M\Omega$ resistor results in a gain of 101, which is within the desired gain tolerance. The gain-frequency characteristic of the amplifier and the feedback network must be such that oscillation does not occur. To meet this condition, the phase shift through amplifier and feedback network must never exceed 180° for any frequency where the gain of the amplifier and the feedback network is greater than unity. In practical applications, the phase shift must not approach 180° because this is the situation of conditional stability. The most critical case occurs when the attenuation of the feedback network is zero.

7.2.3 Application Curve

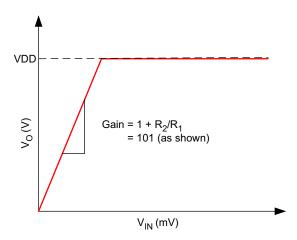


Figure 7-4. Output Response

7.3 Power Supply Recommendations

For proper operation, the power supplies must be decoupled. For supply decoupling, TI recommends placing 10nF to $1\mu F$ capacitors as close as possible to the operational-amplifier power supply pins. For single supply configurations, place a capacitor between the V+ and V- supply pins. For dual supply configurations, place one capacitor between V+ and ground, and place a second capacitor between V- and ground. Bypass capacitors must have a low ESR of less than 0.1Ω .

7.4 Layout

7.4.1 Layout Guidelines

Care must be taken to minimize the loop area formed by the bypass capacitor connection between supply pins and ground. A ground plane underneath the device is recommended; any bypass components to ground must have a nearby via to the ground plane. The optimum bypass capacitor placement is closest to the corresponding supply pin. Use of thicker traces from the bypass capacitors to the corresponding supply pins can lower the power-supply inductance and provide a more stable power supply.

The feedback components must be placed as close as possible to the device to minimize stray parasitics.

7.4.2 Layout Example

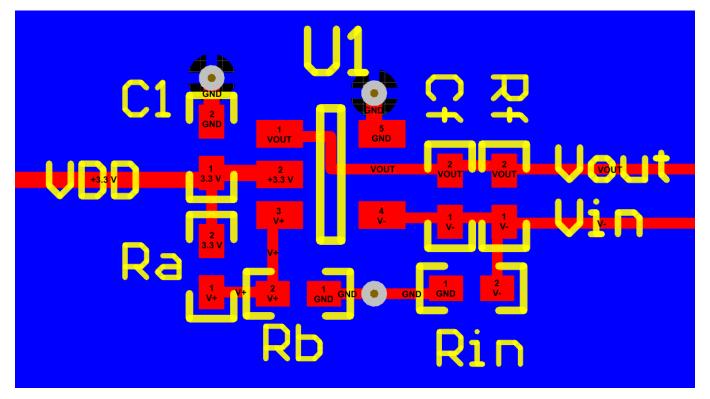


Figure 7-5. LMC7101Q-Q1 Example Layout



8 Device and Documentation Support

8.1 Documentation Support

8.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, LMC66x CMOS Dual Operational Amplifiers data sheet
- Texas Instruments, RES11A Matched, Thin-Film Resistor Dividers With 1kΩ Inputs data sheet

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on Notifications to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

8.4 Trademarks

TI E2E[™] is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	hanges from Revision G (September 2015) to Revision H (January 2025)	Page
•	Moved LMC7101 commercial device into new SBOSAL2 data sheet	1
•	Updated Features	1
•	Updated Description	<mark>1</mark>
•	Updated pin diagram figure and pin names in Pin Configuration and Functions	
•	Deleted Machine model (MM) from ESD Ratings	3
•	Changed temperature test conditions from junction temperature, T _J to ambient temperature, T _A through	out3
•	Updated Thermal Information	3
•	Updated formatting across all Electrical Characteristics	<mark>4</mark>
•	Updated parameter names to be consistent with modern data sheets	<mark>4</mark>
•	Added missing input offset voltage drift temperature condition in all Electrical Characteritics	4
•	Updated temperature range conditions in input bias current and input offset current in all Electrical	
	Characteristics	4
•	Changed input common-mode voltage condition from CMRR ≥ 50dB to CMRR ≥ 47dB	
•	Changed CMRR MIN from 50dB to 47dB	4
•	Deleted footnotes 1 and 2 in all Electrical Characteristics	

www.ti.com

 Changed input common-mode voltage condition from CMRR > 50dB to CMRR > 47dB 	5
Changed CMRR MIN from 60dB to 47dB and TYP from 74dB to 70dB	
Changed CMRR MIN from 60dB to 52dB and TYP from 82dB to 75dB	
• Changed CMRR MIN for $T_A = -40^{\circ}$ C to +125°C from 60dB to 51dB and TYP from 82dB to 74dB	
• Changed input common-mode voltage test condition from (V+) = 5V to (V+) = 15V	<mark>7</mark>
Changed CMRR MIN from 65dB to 62dB	
Deleted Figures 6, 11, 14, 17, 20, 23, and 37	9
Added Figure 5-6	
Added Figures 5-21 and 5-25	13
Updated description text in Size	
Updated Figure 7-3, Example Application to show correct noninverting circuit	
Changes from Revision F (March 2013) to Revision G (September 2015)	Page
 Added Pin Configuration and Functions, ESD Ratings, Feature Description, Device Functional Mode. Application and Implementation, Power Supply Recommendations, Layout, Device and Documentation 	s, on
Support, and Mechanical, Packaging, and Orderable Information sections	1
Changes from Revision E (March 2013) to Revision F (March 2013)	Page
Changed layout of National Semiconductor Data Sheet to TI format	23

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

www.ti.com 7-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	pe Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking	
	(1)	(2)			(3)	Ball material	Peak reflow		(6)	
						(4)	(5)			
LMC7101QM5/NOPB	Obsolete	Production	SOT-23 (DBV) 5	-	-	Call TI	Call TI	-40 to 125	AT6A	
LMC7101QM5X/NOPB	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	AT6A	
LMC7101QM5X/NOPB.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	Call TI	Level-1-260C-UNLIM	-40 to 125	AT6A	
LMC7101QM5X/NOPB.B	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	Call TI	Level-1-260C-UNLIM	-40 to 125	AT6A	

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

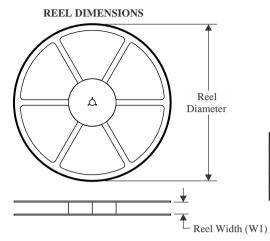
⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

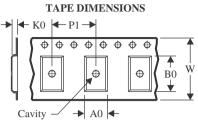
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Sep-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

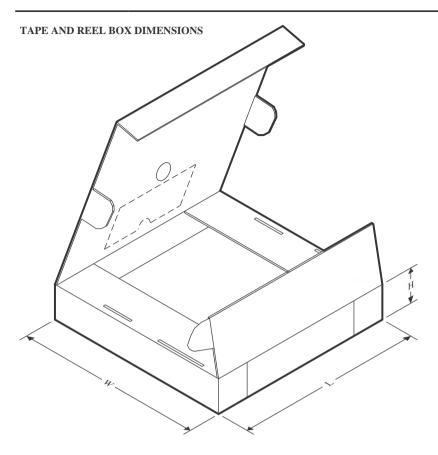


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMC7101QM5X/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Sep-2025

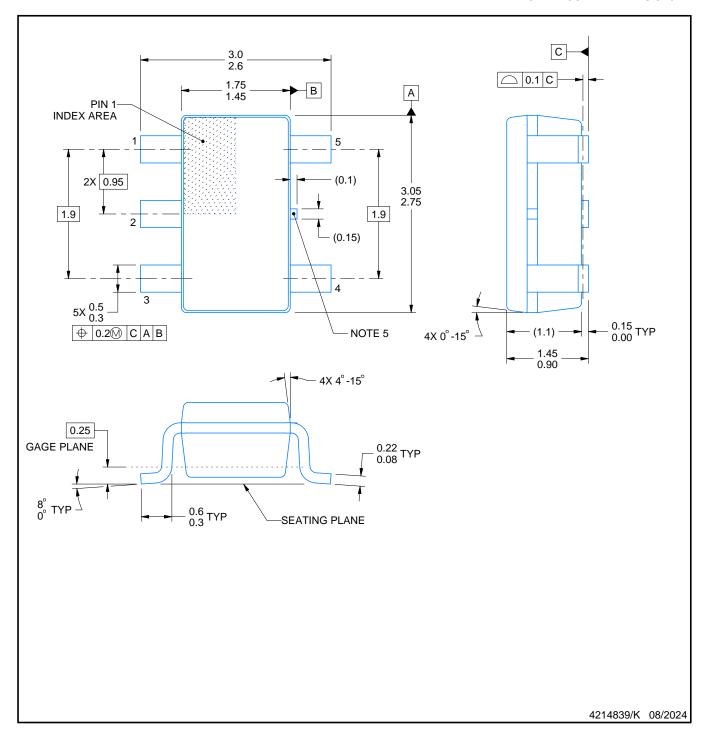


*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	LMC7101QM5X/NOPB	SOT-23	DBV	5	3000	208.0	191.0	35.0	



SMALL OUTLINE TRANSISTOR



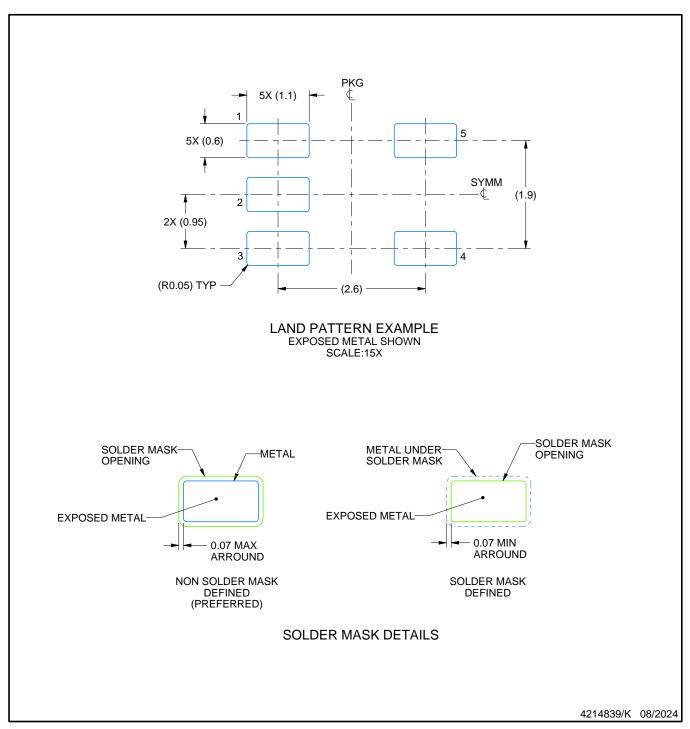
NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



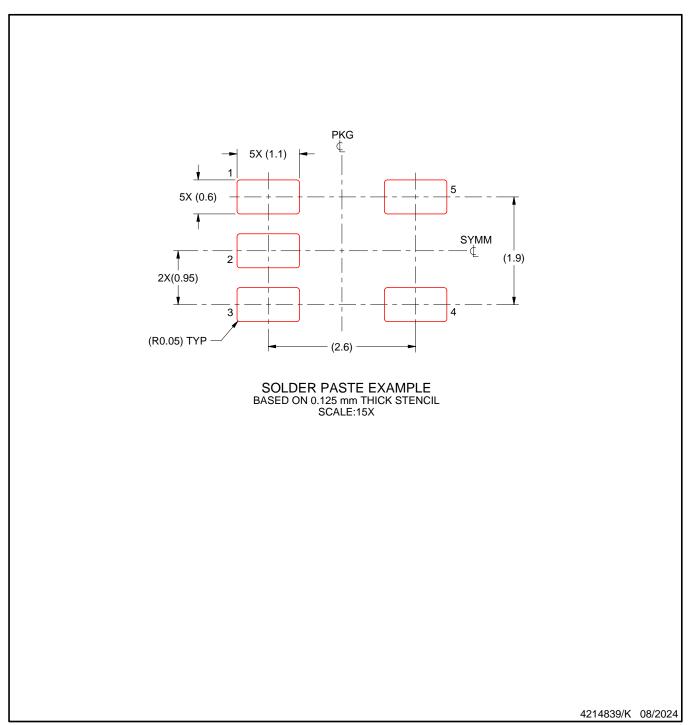
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025